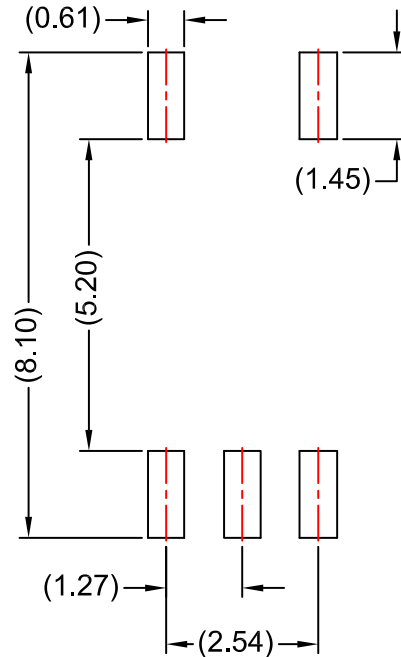
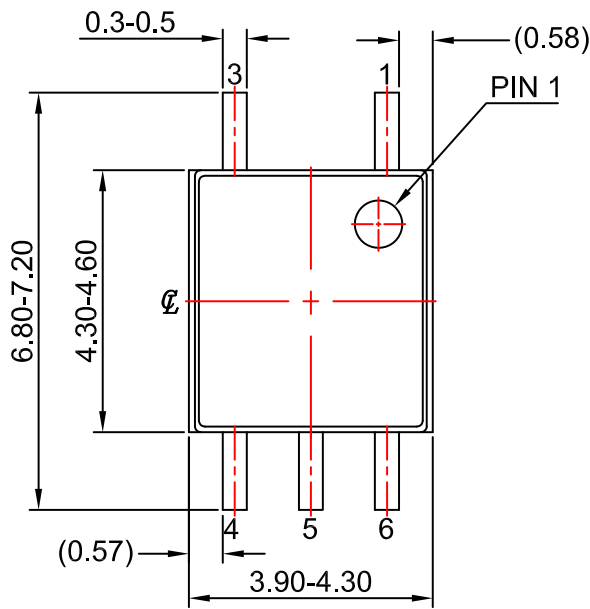


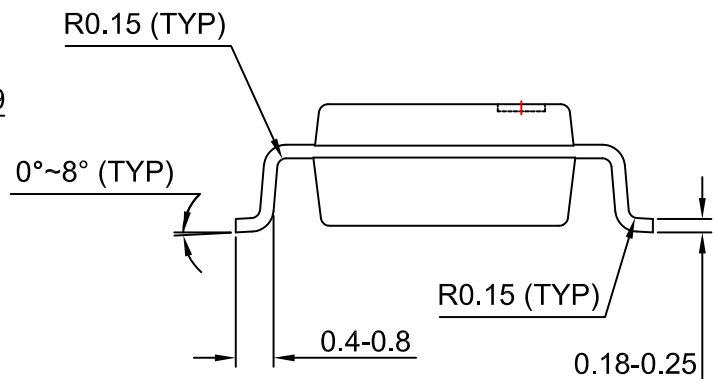
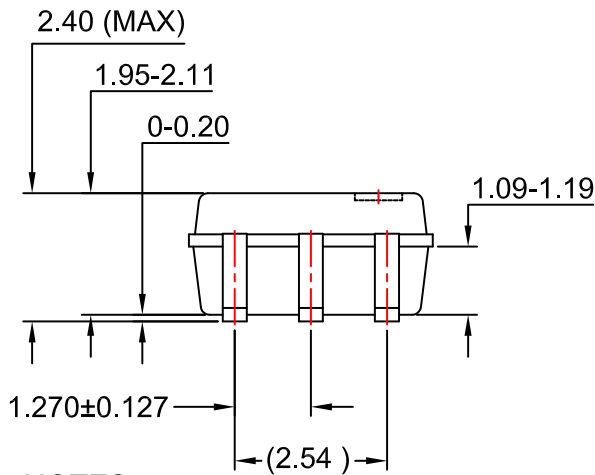
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

MFP5 4.1X4.4, 2.54P  
CASE 100AM  
ISSUE 0

DATE 31 AUG 2016



**LAND PATTERN RECOMMENDATION**



**NOTES:**

- A) NO STANDARD APPLIES TO THIS PACKAGE
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

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